

Terratek®

HC200600

Product Description

Terratek® HC200600 is a proprietary blend of hemp and biobased polyethylene for injection molding applications.

Sustainability Guide	
Biobased content ASTM 6866	-
Biobased content by weight	-
Recycled content	-
Energy use	-
Compostable	-

Property	Test Method	Value
Specific Gravity	ASTM D792	0.91 g/cm3
Shrinkage		0.013 in/in
Melt Index (230C 2.16kg)	ASTM D1238	16.5 g/10 min
Tensile Strength	ASTM D638	4,293 psi
Tensile Modulus	ASTM D638	326,983 psi
Flex Strength	ASTM D790	6,797 psi
Flex Modulus	ASTM D790	243,384 psi
Elongation		3.2 %
Notched Izod	ASTM D256	0.78 ft lb/in

General Processing Recommendations

Green Dot's Terratek® HC200600 resin needs to be dried before processing if the moisture is above 0.5%. Resin will dry quickly at 150°F in a desiccant dryer. Avoid prolonged resin exposure to air during molding or storage as the material can pick up moisture.

For best molding results, larger gates and runners are recommended. The injection pressure required to fill the mold is much higher than typical injection molding grade plastics. Typical injection molding temperatures are listed below, these are only a guide and may need to be changed based on the particular application:

Rear	350°F to 360°F
Middle	350°F to 360°F
Front	360°F to 375°F
Nozzle	360°F to 375°F
Mold	60°F to 170°F

The melt temperature of the resin should remain below 400°F to prevent the material from discoloring and having a burnt odor.

Packaging and Storing

Terratek® HC200600 resin is typically packaged in a sealed plastic-lined Gaylord at 1200 lbs/Gaylord. The product should be stored in a cool, dry, and sanitary area to achieve maximum stability.

The information and recommendations in this sheet are based on our experience and analysis using standard procedures, and are believed to be accurate and reliable. However, they serve merely as typical guides, and are presented in good faith for the benefit of our customers. No guarantee, expressed or implied, is made regarding accuracy of the analysis, patent infringement, liabilities, or risks involved from the application of our products.	Issued:	9/15/15
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